ASSOCIATION CONNECT	© Copyright 2005. IPC, B	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		, , , , , , , , , , , , , , , , , , ,				Type * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Infor	rmation												
Company name* Company			ompany unique ID			Unique ID Authority				Response Date*			
nsemi										2023-06-08			
Contact Name Title - Contact					Phone - Contact*			Email -	Email - Contact*				
Product-Env-Ste	wards	Prod	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
authorized Repre	esentative*	- Representative		P	Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item Numb	em Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	7WB3126MUTA		AG 2 BIT TRANSLATING BUS SW		W	2023-06-08		MY1		3.25	mg	Each	
<b>Ianufacturin</b>	g Proccess Information		,										
Termin	Terminal Plating / Grid Array Material		Terminal Base Alloy J-S		SL Rating	Peak Proces	eak Process Body Temperature Max Time at Peak		t Peak Tempera	Temperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		(no CU Alle	CU Alloy 1			260	С	30		seconds 3			
Comments		-											
vel 1 - maximun	n time at peak temperature du	ıring solderinş	g is 10-30 seconds										
or more informa	ation regarding material comp	position please	e refer to page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.17	mg	Supplier	Silicon (Si)	7440-21-3		0.17	mg
Die Attach	0.12	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0384	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0816	mg
Lead Frame	0.73	mg	Supplier	Zinc (Zn)	7440-66-6		0.0007	mg
			Supplier	Iron (Fe)	7439-89-6		0.0161	mg
			Supplier	Copper (Cu)	7440-50-8		0.7132	mg
Mold Compound-Black	2.15	mg		Epoxy Phenol Resin	proprietary data		0.1935	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.9565	mg
Plating	0.01	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			В	Nickel (Ni)	7440-02-0		0.0096	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg